



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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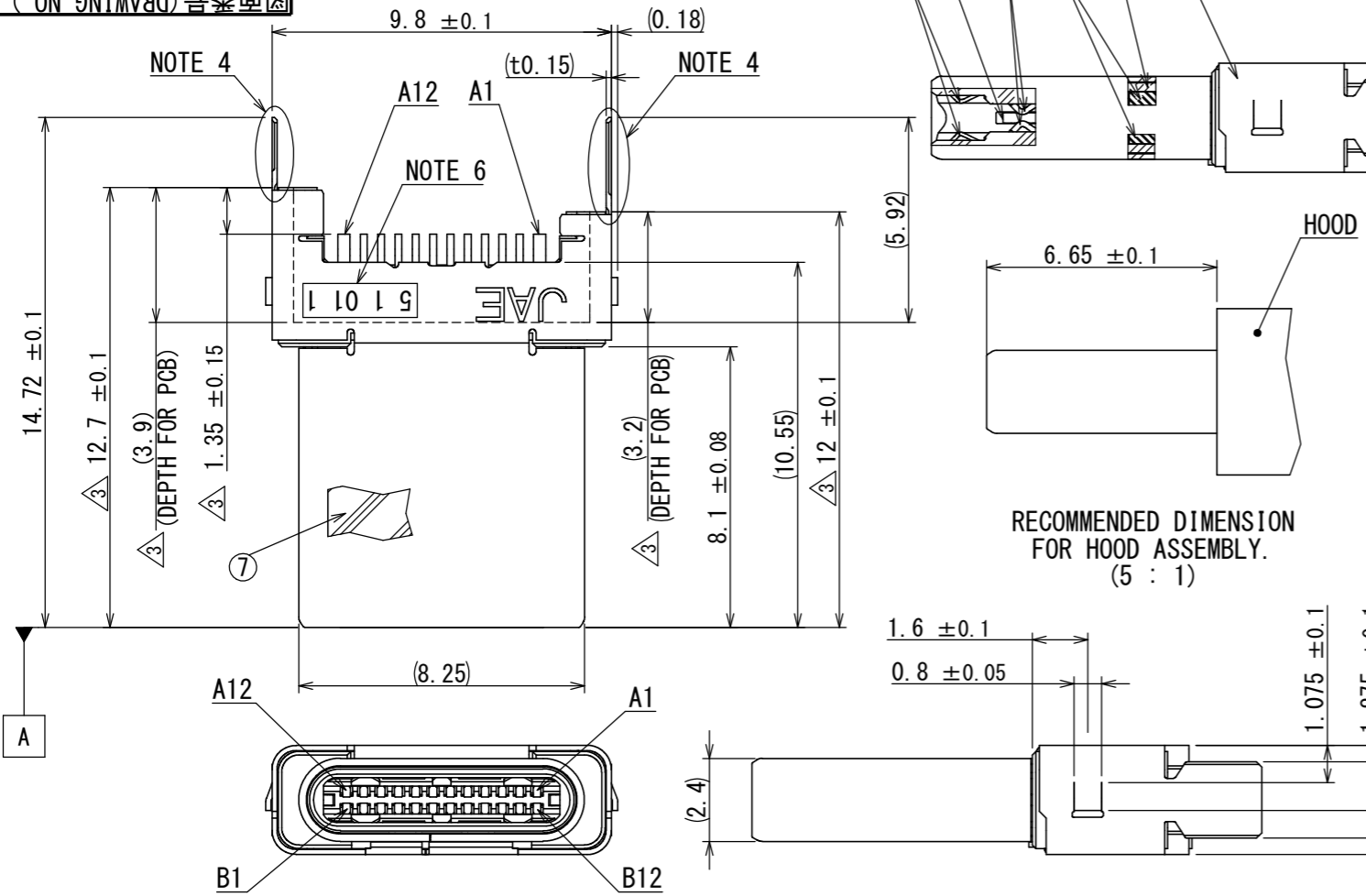
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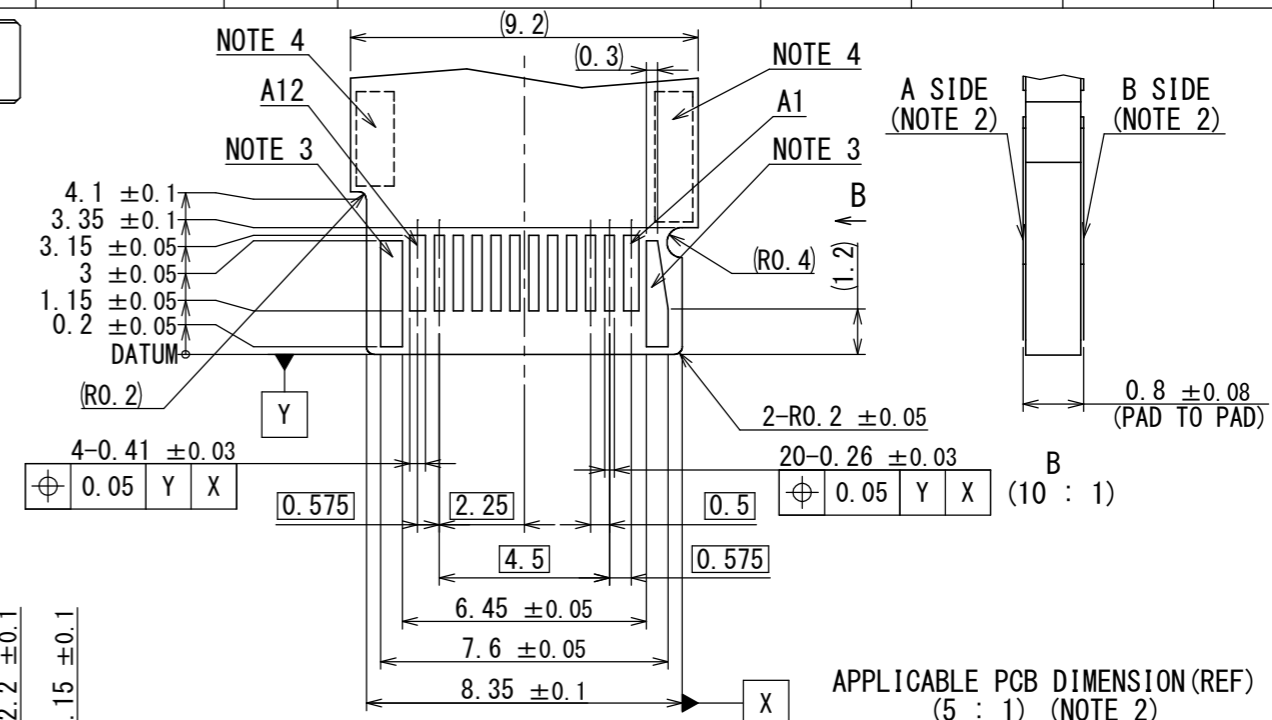


SJ115803
(ON DRAWING NO.)

版数 VER.	年月日 DATE	CN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	24/JUL/2015	014075	ADDED LASER WELDING		K. UEDA	—	Y. SAITOU
3	25/SEP/2015	014607	REVISED DIMENSION		K. UEDA	—	Y. SAITOU

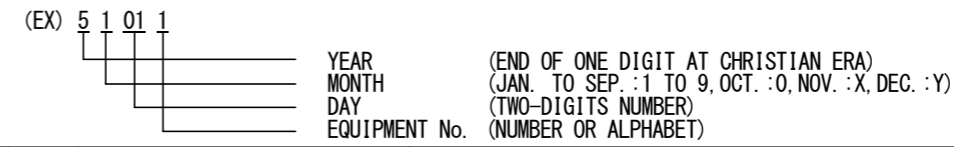


RECOMMENDED DIMENSION
FOR HOOD ASSEMBLY.
(5 : 1)

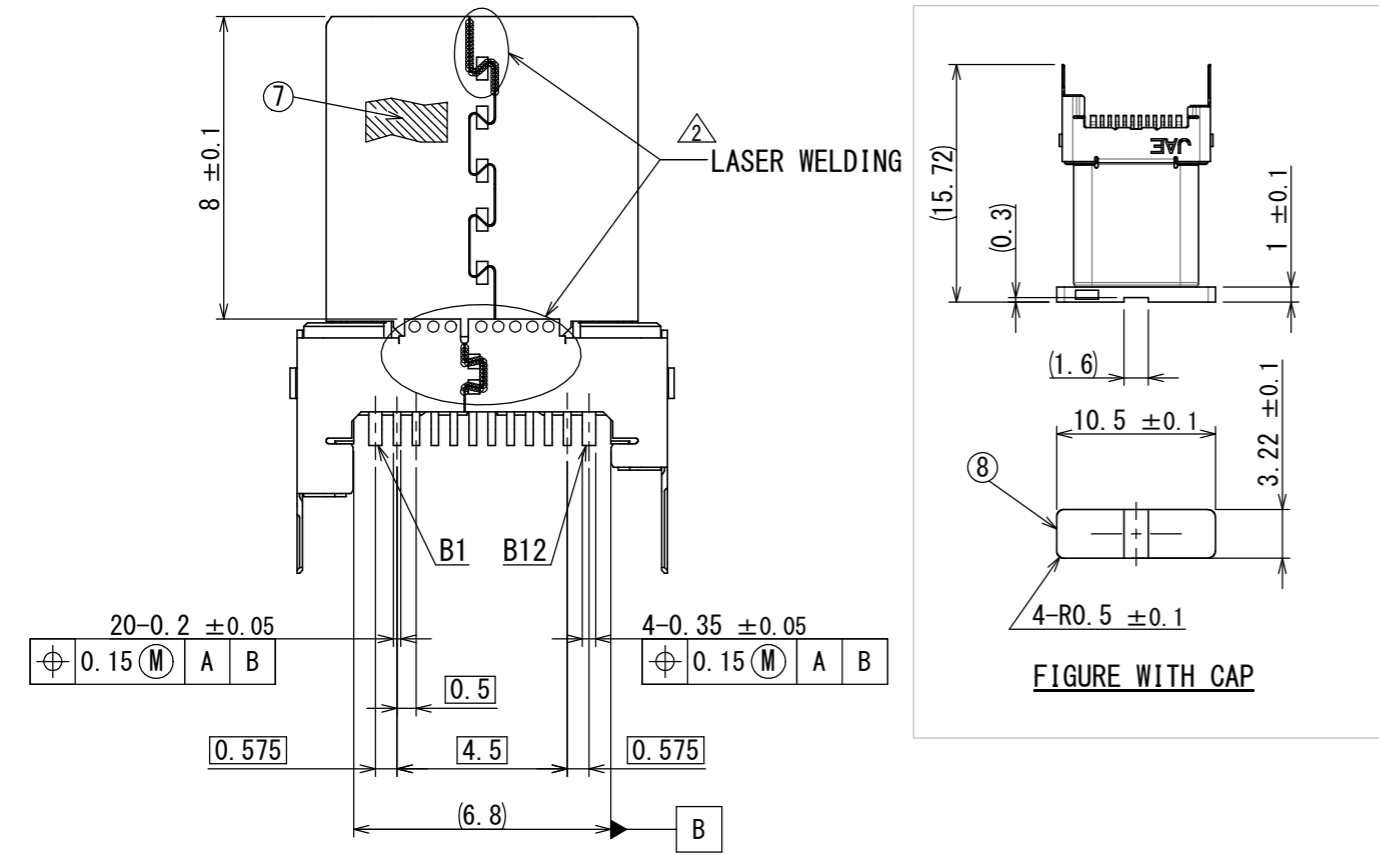


APPLICABLE PCB DIMENSION (REF)
(5 : 1) (NOTE 2)

- NOTE 1. THERE COULD BE UNRECOGNIZABLE DIFFERENCES FROM ACTUAL PRODUCT DUE TO PROCESS CONVENIENCE BUT NOT IMPACT ON THE FUNCTION.
- NOTE 2. PCB PADS CONFIGURATION BE SAME BETWEEN A SIDE AND B SIDE.
- NOTE 3. THERE PADS BE WHERE A CONNECTOR HOLDS PCB. SHALL NOT BE ELECTRICAL USE NOT SOLDERED.
- NOTE 4. RECOMMEND TO UTILIZE THE SIDE SHELL TABS BY SOLDERING TO PCB PADS FOR THE MECHANICAL STRENGTH.
- NOTE 5. RECOMMEND TO KEEP THE CAP STAY IN PLACE UNTIL ALL THE PROCESSES DONE. THE CAP PREVENTS A CONNECTOR FROM DEFORMED AND CONTAMINATION DURING PROCESSES SUCH AS PADDLE CARD ASSEMBLY AND CABLE ASSEMBLY.
- NOTE 6. LOT NUMBER IS MARKED AS INDICATED.



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
8	CAP	1	HEAT RESISTING PLASTIC	(BLACK)	
7	TAPE	2	POLYIMIDE	-	
6	SHELL	1	STAINLESS STEEL	NICKEL PLATING	
5	GROUND SPRING	2	STAINLESS STEEL	NICKEL PLATING	
4	LOCK	1	STAINLESS STEEL	-	
3	INSULATOR B	2	HEAT RESISTING PLASTIC	(BLACK)	
2	INSULATOR A	1	HEAT RESISTING PLASTIC	(BLACK)	
1	CONTACT	24	COPPER ALLOY	CONTACT AREA: GOLD FLASH OVER PALLADIUM-NICKEL OVER NICKEL SOLDER TAILS: GOLD FLASH OVER NICKEL	



仕様書 (SPECIFICATION) JACS-30353 JAHL-30353	第1版 (ORIGINAL DATE) 16/MAR/2015	尺度 (SCALE) 5:1	シリーズ (SERIES) DX07	日本航空電子工業株式会社 JAE
一般公差 (GENERAL TOLERANCE) 寸法 (DIMENSION) × ± 0.8 × × ± 0.4 × × × ± 0.1 × × × × ±	角度 (ANGLES) ×° ± ×° ×' ±	製図 DR. —	名称 (TITLE) DX07P024MJ1	JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
単位 (UNIT) : mm	担当 CHK. Y. SAITOU	査閲 APPD. —	承認 APPD. T. MASUMOTO	図面番号 (DRAWING NO.) SJ115803

WISDOM承認 2015/09/29

DCF-C-212H(12.08)